


# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	ADG/23/14027
1.3 Title of PCN	SPC58xN8xC3x (FG84): BGA 17x17 Activation of ASE as Additional Assembly Plant
1.4 Product Category	see list
1.5 Issue date	2023-05-09

## 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Luca RODESCHINI
2.1.2 Marketing Manager	Matteo MOIOLI
2.1.3 Quality Manager	Alberto MERVIC

## 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Subcon ASE - Taiwan receiving Plant

## 4. Description of change

	Old	New
4.1 Description	ST Kirkop - Malta Assy Plant	ST Kirkop - Malta and ASE - Taiwan Assy Plants
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

## 5. Reason / motivation for change

5.1 Motivation	Capacity Increase
5.2 Customer Benefit	CAPACITY INCREASE

## 6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Good Codes
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## 7. Timing / schedule

7.1 Date of qualification results	2023-12-15
7.2 Intended start of delivery	2023-12-29
7.3 Qualification sample available?	Upon Request

## 8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results		In progress	Issue Date

## 9. Attachments (additional documentations)

14027 Public product.pdf
14027 Details.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SPC58NN84C3RMHBR	

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## PRODUCT/PROCESS CHANGE NOTIFICATION

<b>TITLE</b>	<b>SPC58xN8xC3x (FG84): BGA 17x17 Activation of ASE as Additional Assembly Plant</b>																			
<b>IMPACTED PRODUCTS</b>	<b>FPBGA 17X17X1.8:</b>   FG84 – Bernina 6M																			
<b>MANUFACT. STEP</b>	Assembly																			
<b>INVOLVED PLANT</b>	Subcontractor ASE – Taiwan																			
<b>CHANGE REASON</b>	Service – Dual source & Capacity Improvement. Expansion of current assembly and testing capacity (volumes increase) and flexible/secure production asset – dual sourcing strategy.																			
<b>CHANGE DESCRIPTION</b>	Activation of ASE as additional BE Assembly plant.  Here below package Bill Of Material comparison <table border="1"> <thead> <tr> <th></th><th>Malta</th><th>ASE</th></tr> </thead> <tbody> <tr> <td><b>Substrate</b></td><td>HL832NS</td><td>HL832NS</td></tr> <tr> <td><b>Glue</b></td><td>2000S</td><td>2100A</td></tr> <tr> <td><b>Resin</b></td><td>GE-100LF1-2V</td><td>EME-G750SE</td></tr> <tr> <td><b>Wire</b></td><td>Cu Pd 0.7 mil</td><td>Cu Pd Au 0.7 mil</td></tr> <tr> <td><b>Package ball</b></td><td>Ball Diam 0.55mm / Alloy SACN38855</td><td>Ball Diam 0.55mm / Alloy SACN38855</td></tr> </tbody> </table>			Malta	ASE	<b>Substrate</b>	HL832NS	HL832NS	<b>Glue</b>	2000S	2100A	<b>Resin</b>	GE-100LF1-2V	EME-G750SE	<b>Wire</b>	Cu Pd 0.7 mil	Cu Pd Au 0.7 mil	<b>Package ball</b>	Ball Diam 0.55mm / Alloy SACN38855	Ball Diam 0.55mm / Alloy SACN38855
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<b>TRACEABILITY</b>	Dedicated Finished Good Codes																			

<b>VALIDATION</b>	According to ZVEI (AEC-Q100/Q006) recommendations, items: <ul style="list-style-type: none"> <li>- SEM-PA-07 (<i>Die Attach material</i>)</li> <li>- SEM-PA-08 (<i>Change of wire bonding</i>)</li> <li>- SEM-PA-11 (<i>Change of mold compound / encapsulation material</i>)</li> <li>- SEM-PA-18 (<i>Move all or part of production to a different assembly site</i>)</li> </ul>
<b>CURRENT PRODUCTS</b>	Current products assembly and testing will be transferred to ASE. ST assembly plants will remain active as alternative solution.
<b>REPORTS</b>	Transfer validation is presently in progress. Transfer validation report will be available within Q4 – 2023
<b>IMPLEMENT.</b>	The Start of Production is foreseen for Q4 - 2023



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** SPC58xN8xC3x (FG84): BGA 17x17 Activation of ASE as Additional Assembly Plant

**PCN Reference :** ADG/23/14027

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

SPC58NN84C3RMHBR	SPC58NN84C3RMHBY	
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